

LINEAR TECHNOLOGY MATERIALS DECLARATION

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(Engineering Calculation)

MSOP-Exposed

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TOTAL MASS (g) : 0.036873

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.002332 | 1000000 | 63244.0664062 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.013845 | 975000 | 375477.75 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000341 | 24000 | 9247.953125 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000004 | 300 | 108.480384827 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000010 | 700 | 271.200958252 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.014200 | 1000000 | 385105.375 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.000710 | 1000000 | 19255.9453125 | | |
| | | External Plating Total: | | | | 0.000710 | 1000000 | 19255.9453125 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000086 | 1000000 | 2332.32836914 | | |
| Internal Plating Total: | | | | 0.000086 | 1000000 | 2332.32836914 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000395 | 820000 | 10712.4394531 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000087 | 180000 | 2359.44848633 | | |
| Die Attach Total: | | | | 0.000482 | 1000000 | 13071.8867188 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.002439 | 130000 | 66145.921875 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.015571 | 830000 | 422287.0625 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000657 | 35000 | 17817.9023438 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000094 | 5000 | 2549.28930664 | | |
| | | Encapsulation Total: | | | | 0.018761 | 1000000 | 508800.15625 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000302 | 1000000 | 8190.26953125 | | |
| | | | | | TOTAL MASS (g) : | 0.036873 | | |